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U.S. Patent Application Serial No. 10/607,514  
Amendment dated April 23, 2007  
Response to Official Action dated January 23, 2007

**Amendments to the Claims:**

The following listing of claims replaces all prior versions and listings of the claims in this application.

**Listing of the Claims:**

1. - 28. (Cancelled).

29. (Previously Presented) A radiation cured encapsulating material having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi.

30. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5%.

31. (Previously Presented) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 1.10 pounds force, a percent elongation at break of at least about 10%, and an adhesion force to an underlying surface material of greater than about 0.011 pounds force.

32. (Previously Presented) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 0.44 pounds force, a percent elongation at break of at least about 20%, and an adhesion force to an underlying surface material of greater than about 0.015 pounds force.

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33. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, formed by radiation curing a composition comprising from about 30 to about 80 weight percent of a polyether-based urethane acrylate oligomer, from about 1 to about 40 weight percent of isocyanurate monomer having a plurality of acrylate or methacrylate groups, and an effective amount of a photoinitiator for radiation curing the composition upon exposure to curing radiation.

34. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer.

35. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

36. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi, formed by radiation curing a composition comprising from about 40 to about 75 weight percent of the polyether-based urethane acrylate oligomer, from about 10 to about 30 weight percent of the isocyanurate monomer having a plurality of acrylate or methacrylate groups, and from about 0.1 to about 20 weight percent of the photoinitiator for radiation curing the composition upon exposure to curing radiation.

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37. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi, formed by radiation curing a composition comprising from about 50 to about 75 weight percent of the polyether-based urethane acrylate oligomer, from about 15 to about 30 weight percent of the isocyanurate monomer having a plurality of acrylate or methacrylate groups, and from about 1 to about 10 weight percent of the photoinitiator for radiation curing the composition upon exposure to curing radiation.

38. (Previously Presented) A radiation cured encapsulating material as defined by claim 37, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer and the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

39. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force.

40. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force.

41. - 43. (Cancelled).

44. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5%.

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45. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 10%.

46. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 20%.

47. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force and a percent elongation at break of at least about 10%.

48. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force and a percent elongation at break of at least about 20%.

49. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a viscosity-reducing component in an amount sufficient to lower the viscosity of the composition.

50. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a coefficient of friction reducing component in an amount sufficient to lower the coefficient of friction of the radiation cured material.

51. - 52. (Cancelled).

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53. (New) A radiation cured encapsulating material as defined by claim 33, formed by radiation curing a composition comprising from about 50 to about 80 weight % of a polyether-based urethane acrylate oligomer, from about 15 to about 40 weight % of isocyanurate monomer having a plurality of acrylate or methacrylate groups, and from about 1 to about 10 weight % of photoinitiator for radiation curing the composition upon exposure to curing radiation.